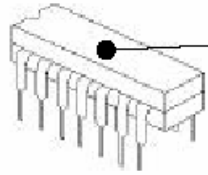


# Top Marking Information for Mil/Aero Products



## TOP MARK INFORMATION

(Not all marks shown may appear on parts)

**Plant of Manufacture Code for Military Products**

First Digit: Country Code

Malacca	M
Philippines	H
Santa Clara	F
Singapore	S
South Portland	Z
USA Subs	X

**883 & 38510 Date Code**

2nd digit: Last digit of the year wafer sort was performed.

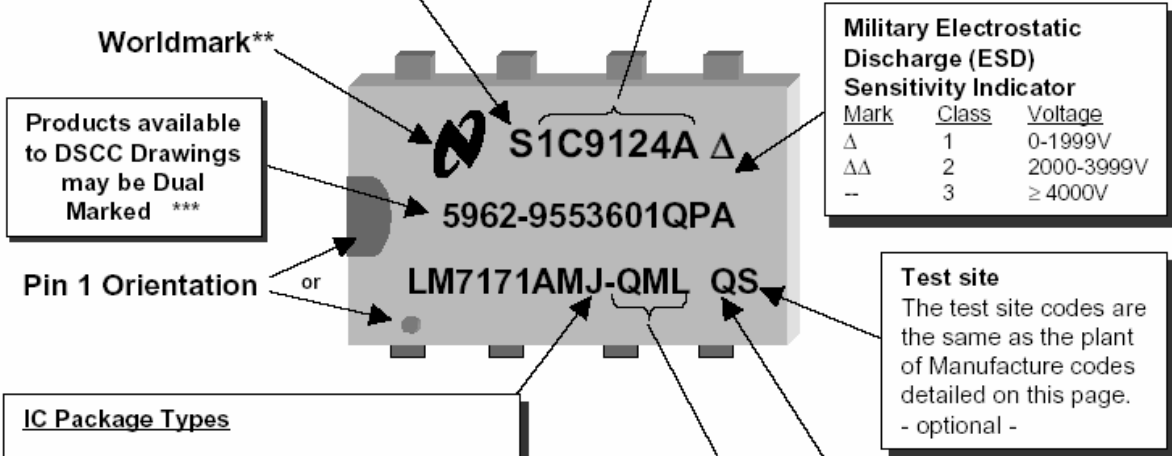
3rd digit: Alpha character indicating the calendar quarter in which wafer sort was performed.

Character	Months	Weeks
A	Jan-Mar	1 -13
B	Apr - June	14 -26
C	Jul-Sept	27 -39
D	Oct-Dec	40 -53
GF	Prior to 1988	

4th & 5th digits: Calendar year

6th & 7th digits: Sealweek

8th digits: Alpha character indicating the lot is a sub-lot (when applicable).



**IC Package Types**

D	Glass/ Metal DIP
DM	Ceramic DIP
F	Glass/ Metal Flatpak (1/4x1/4)
FM	Flat pack
G	12 Lead TO-8 CAN
H	Multi- Lead CAN
J	Lo-Temp Ceramic DIP ('Fit-Seal' Package)
J-8	8 Load Ceramic DIP ('MiniDIP' Package)
K	TO-3 CAN in Steel, except LM309K which is shipped in Aluminium Ksteel TO-3 CAN (Steel)
L	Ceramic Leaded Chip Carrier
LM	Ceramic Leadless Chip Carrier (LCC)
U	Pin Grid Array
W	Lo-Temp Ceramic Flatpack
WG	Ceramic SOIC

**Part number**

**Device suffix**

/883	Compliant to MIL-STD-883
QB:	MIL-STD-883*
-QML	QML
-QMLV	Space level QML
-MLS	Non QMLV space
-MIL	Non compliant B level

Note: Some products using the 'QB' designator may not be compliant to MIL-STD-883. Contact NSC Sales Office for details.

\*\* Parts manufactured before June 1, 1994 may have old logo.

\*\*\* Marking in accordance with DSCC conventions